

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT4971303

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHENG-PANG CHAN	05/11/2018
CHIEN-MING WU	05/11/2018
LIANG-HUAN LEI	05/11/2018
JIAN-RU LIN	05/11/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	REALTEK SEMICONDUCTOR CORP.
<b>Street Address:</b>	NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15985653
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)574-5876
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<b>Correspondent Name:</b>	LI&CAI INTELLECTUAL PROPERTY(USA) OFFICE
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<b>ATTORNEY DOCKET NUMBER:</b>	106P000947US
<b>NAME OF SUBMITTER:</b>	ZHUO XU
<b>SIGNATURE:</b>	/ZHUO XU/
<b>DATE SIGNED:</b>	05/21/2018
<b>Total Attachments: 3</b>	
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**ASSIGNMENT DEED**

Attorney docket No. 106P000947US

This Assignment agreement is applicable to an invention entitled (invention Title):

IMPEDANCE CALIBRATION DEVICE AND METHOD THEREOF

The PATENT RIGHTS referred to in this agreement are:

(Check one)

- a Patent Application for this invention, executed by the ASSIGNOR(S) concurrently with this Assignment
- U.S. Patent Application Serial No. \_\_\_\_\_, filed \_\_\_\_\_
- U.S. Patent No. \_\_\_\_\_, issued \_\_\_\_\_

The PATENT RIGHTS assigned under this agreement are:

(Check One)

- U.S. Patent rights only
- worldwide Patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. Patent Application identified above.

I/WE believe that I/WE am/are the original inventor(s) of a claimed invention in the application.

The above-identified Application was made or authorized by me/us.

I/WE hereby acknowledge that any will false statements made in this Assignment is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

The ASSIGNOR(S) referred to in this agreement is (or are):

(Full name of sole or first assignor) CHENG-PANG CHAN (FAMILY NAME: CHAN)

(Address) 11F., NO.2, LN. 19, GUANXIN RD., EAST DIST., HSINCHU CITY 300, TAIWAN, R.O.C.

(Full name of second joint assignor) CHIEN-MING WU (FAMILY NAME: WU)

(Address) 13F.-3, NO.177, KEDA 1ST RD., ZHUBEI CITY, HSINCHU COUNTY 302, TAIWAN, R.O.C.

(Full name of third joint assignor, if any) LIANG-HUAN LEI (FAMILY NAME: LEI)

(Address) NO.21, ALY. 1, LN. 41, XINJIANG RD., GUSHAN DIST., KAOHSIUNG CITY 804, TAIWAN, R.O.C.

(Full name of fourth joint assignor, if any) JIAN-RU LIN (FAMILY NAME: LIN)

(Address) NO.3-2, TAIPING LN., MINGJIAN TOWNSHIP, NANTOU COUNTY 551, TAIWAN, R.O.C.

(Full name of fifth joint assignor, if any) \_\_\_\_\_

(Address) \_\_\_\_\_

- Additional assignors are being named on separately numbered sheets attached hereto.

The sole or first ASSIGNEE(S) referred to in this agreement is (or are):

(Name of Assignee) REALTEK SEMICONDUCTOR CORP.  
(Address of Assignee) NO.2, INNOVATION ROAD II, HSINCHU SCIENCE PARK, HSINCHU 300, TAIWAN, R.O.C.

The sole or first ASSIGNEE is: (Check One)

- an individual  
 a partnership  
 a Corporation of TAIWAN, R.O.C. (State or Country)

The second ASSIGNEE(S) (if any) referred to in this agreement is (or are):

(Name of Assignee) \_\_\_\_\_  
(Address of Assignee) \_\_\_\_\_

The second ASSIGNEE is: (Check One)

- an individual  
 a partnership  
 a Corporation of \_\_\_\_\_ (State or Country)

The third ASSIGNEE(S) (if any) referred to in this agreement is (or are):

(Name of Assignee) \_\_\_\_\_  
(Address of Assignee) \_\_\_\_\_

The third ASSIGNEE is: (Check One)

- an individual  
 a partnership  
 a Corporation of \_\_\_\_\_ (State or Country)

Additional assignees are being named on separately numbered sheets attached hereto.

The ASSIGNOR(S), in consideration of \$1.00 paid by each ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, have and do hereby assign the following to each ASSIGNEE; their successors and assigns:

the full and exclusive right to the invention;

an equal interest in and to the entire right, title, and interest in and to the PATENT RIGHTS in the invention, and all continuation, continuation-in-part, divisional, re-issue, and re-examination patents and patent applications relating to the PATENT RIGHTS; and

the right to claim priority under 35 U.S.C. § 119, based on any earlier foreign applications for this invention.

As to all U.S. Patent Applications assigned under this Agreement, the ASSIGNOR(S) hereby authorize(s) and

request(s) the Director of Patents and Trademarks to issue all Letters Patent to the ASSIGNEE(S) as the ASSIGNEE(S) of an equal interest in the entire right, title, and interest, for the sole use and enjoyment of said ASSIGNEE(S), their successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE(S), or their representatives, any facts known to the ASSIGNOR(S) respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination, and reissue applications, execute all necessary assignment papers to cause any and all Letters Patent to be issued to said ASSIGNEE(S), make all rightful oaths, and generally do everything necessary or desirable to aid said ASSIGNEE(S), their successors and assigns, to obtain and enforce proper protection for said invention.

I/WE hereby give our Attorney authorization to insert the Serial Number and filing date of the above-referenced Patent Application when known.

CHENG-PANG CHAN (FAMILY NAME: CHAN)

Cheng Pang Chan  
(Signature of sole or first assignor)

May 11, 2018

(Date)

CHIEN-MING WU (FAMILY NAME: WU)

Chien-Ming Wu  
(Signature of second assignor, if any)

May 11, 2018

(Date)

LIANG-HUAN LEI (FAMILY NAME: LEI)

Liang-Huan Lei  
(Signature of third assignor, if any)

May 11, 2018

(Date)

JIAN-PU LIN (FAMILY NAME: LIN)

JIAN-PU LIN  
(Signature of fourth assignor, if any)

May 11, 2018

(Date)

\_\_\_\_\_  
(Signature of fifth assignor, if any)

(Date)